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Requirements for Printed Electronics Functional Conductive Materials

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An international standard developed by IPC

Association Connecting Electronics Industries

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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Keep people out
- Increase cycle time
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Requirements for Printed Electronics Functional Conductive Materials

Developed by the D-63 Printed Electronics Functional Materials Subcommittee of the D-60 Printed Electronics Committee of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Acknowledgment

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Printed Electronics Committee

Co-Chairs
Neil Bolding, MacDermid Enthone Electronics Solutions

Daniel Gamota, Printovate Technologies, Inc.

Printed Electronics Functional Materials Subcommittee

Chair
Josh Goldberg, Rogers Corporation

Technical Liaison of the IPC Board of Directors

Bob Neves
Microtek (Changzhou) Laboratoris

Printed Electronics Functional Materials Subcommittee

Leonard Allison, Engineered Materials Systems

Sai Avuthu, Jabil Circuit, Inc.

Neil Bolding, MacDermid Enthone Electronics Solutions

Alan Brown, Engineered Materials Systems, Inc.

Alan Burk, ALMAX

John Crumpton, DuPont - RTP

Mahendra Gandhi, Northrop Grumman Aerospace Systems

Ken Gann, Lab Tech

MaryAlice Gill, Jabil Circuit, Inc.

Josh Goldberg, Rogers Corporatio

Scott Gordon, DuPont Teijin Films

Philip Henault, Raytheon Company

Mary Herndon, Raytheon Compan

Daniel Hines, Laboratory for Physical Sciences

Michael Jawitz, Orbital ATK

Rajesh Kumar, TTM Technologies

Mike Mastropietro, NextFlex

Roger Mi[illegible], Raytheon Company

D[illegible]er, 3M

Jeffrey Parker, Insulectro

HaridossSarma, GO 2 Scout 4 R&T

Jeff Shubrooks, Raytheon Company

[illegible]ichard Snogren, Bristlecone LLC

David Sommervold, The Bergquist Company/Henkel Electronic Materials LLC

Brent Sweitzer, Multek Flexible Circuits, Inc.

Brian Toleno, Microsoft Corporation

Hector Valladares, Honeywell Aerospace

Steve Vetter, NSWC Crane

Diane Williams, Corning Incorporated

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Requirements for Printed Electronics Functional Conductive Materials

1 SCOPE

This standard establishes the classification system and the qualification and quality conformance requirements for functional conductive materials used in printed electronics applications.

1.1 Purpose The purpose of this standard is to provide practitioners of printed electronics with the necessary technical structure to design and manufacture product meeting conformance to industry-determined metrics.

1.2 Classification System The user has the responsibility to specify on the procurement documentation materials capable of meeting the requirements of this specification and end-item use.

Note: When possible, material callout information should be reviewed with the supplier to obtain concurrence that the part will meet customer requirements and, if necessary, to update the procurement documentation accordingly.

The classification system defined in 1.2.1 through 1.2.1.3 identifies functional conductive materials for printed electronics applications.

1.2.1 Functional Conductive Material Designation The functional conductive material designation is intended for use on material purchase orders (see 6.1). Designers **shall** specify on master drawings their material selection only. This is because the specific designation is lengthy and requires fabricator-level knowledge for making the detailed selections.

The functional conductive material designation should be in the form shown of the example below:

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Where:

2 = Postprocessed structure classification (see 1.2.1.1), specifying sintering

A = Postprocessed bulk classification (see 1.2.1.2), specifying metal

1 = Preprocessed conductive classification (see 1.2.1.3), specifying spheres

1.2.1.1 Postprocessed Functional Conductive Material – Structure Classification The postprocessed functional conductive material structure classification **shall** be designated per Table 1-1.

Table 1-1 Postprocessed Functional Conductive Material – Structure Classification

Designation	Type
1	Percolation
2	Sintering
3	Metal organic decomposition
4	Intrinsically conductive polymer
5	Other

1.2.1.2 Postprocessed Functional Conductive Material – Bulk Composition Classification The postprocessed functional conductive material bulk composition **shall** be designated per Table 1-2.

Table 1-2 Postprocessed Functional Conductive Material – Bulk Composition Classification

Designation	Type
A	Metal
B	Metal oxide
C	Organic
D	Allotropes of carbon
E	Other

Table note: For combinations, use multiple letters separated by a slash(es).